

In re Patent Application of:  
COFFA ET AL.  
Serial No. 10/014,880  
Confirmation No. 2364  
Filed: DECEMBER 11, 2001

In the Drawings

Form PTO-948 from the PTO Draftsperson refers to the drawings filed on December 11, 2001. Applicants note that revised formal drawings were filed on February 26, 2002. Accordingly, the Examiner's objection should be withdrawn.

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In the Specification:

Please replace the paragraph beginning at page 8, line 7,  
with the following rewritten paragraph:

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--Thereafter, the trenches are sealed by depositing a  
silicon oxide layer, or sealant layer, by a PVAPOX process and the  
surface is planarized according to common techniques to produce the  
structure of FIG. 3c. On the so planarized surface a backplate  
structure of the sensor is formed according to the known technique  
of first depositing by a PVAPOX process a layer of sacrificial oxide  
26 over the sensor area followed by the deposition of a contouring  
layer of silicon nitride 27 around the perimeter sacrificial oxide  
layer (Fig. 3d). Finally, a layer of polycrystalline silicon 28 of  
the backplate is deposited with a plurality of holes 30 over the  
sacrificial oxide layer 26 and over the perimetral layer of silicon  
nitride 27 as shown in FIG. 3e.--